

Product Description

Shin-Etsu FE-341 U is one of a series of high tensile, high tear fluorosilicone compounds. It is designed to process well in molding applications. It can be blended with other members of the series for intermediate hardnesses.

Product Features

- Excellent fuel and solvent resistance.
- Usable over a broad temperature range.

Typical Applications

- Chemical resistant packings and seals.
- Oil and fuel resistant seals, O rings, diaphragms for automotive.
- Heat and cold resistant packings, gaskets for aeronautical.

Packaging Information

44lb Box

Typical Properties

Type of HCR	Fluorosilicone
Cure Agent	DBPH
Durometer	44
Tensile Strength (psi)	1930
Elongation (%)	545
Specific Gravity	1.41
Tear Die B (ppi)	179
Compression Set (%)	11
Comp. Set Time (hours)	22
Comp. Set Temp. (°C)	180
Comp. Set Temp. (°F)	356
Press Cure/Post Cure	Post
Post Cure Time (hours)	4
Post Cure Temp. (°C)	200
Post Cure Temp. (°F)	392

Note: Values are not for specification purposes.

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